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J. White  
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of

Kenichi HAMANAKA, et al.

Serial No.: 09/854,767

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Group Art Unit: 2832

Examiner: J. A. Zoker

For: ADHESIVE RESIN COMPOSITION AND METHOD  
OF PRODUCING THE SAME, AND CHIP COIL COMPONENT

Asst. Commissioner for Patents  
Washington, D.C. 20231

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